2023-06-08  Contact Name  Title - Contact  Product-Env-Stewards  Product-Enviro Compliance Authorized Representative*  Title - Representative  Phone - Contact*  Email - Contact*  Product-Env-Stewards@onsemi.com  Product-Env-Stewards@onsemi.com  Email - Representative*	IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRIE	© Copyright 2005. II	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name*    Company unique ID   Unique ID Authority   Response Date*	752-21.1					*					als and Mf	g Informat	ion		
nsemi ontact Name Title - Contact Product-Env-Stewards Product-Enviro Compliance Title - Representative Title - Representative Product-Env-Stewards Product-Env-Stewards Product-Enviro Compliance Title - Representative Phone - Representative* Phone - Representative* Phone - Representative* Product-Env-Stewards Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards@onsemi.com NA Naufacturing Site Naufacturing	upplier Inforr	nation													
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Authorized Representative* Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Requester Item Number Mrotecturing Process Information  Terminal Plating / Grid Array Material Matte Tin (Sn) - annealed  Title - Representative  Product Enviro Compliance NA  Requester Item Number Mfr Item Number Mfr Item Name Requester Item Number Mfr Item Name Representative* NA  Product-Env-Stewards@onsemi.com Weight* UOM  142.69 mg  Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycle Matter Tin (Sn) - annealed CU Alloy  1 260 C 30 seconds 3	ontact Name		Title - Contact			]	Phone - Contact*				Email - Contact*				
Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM MC74LVX259DG LOG CMOS 8-BIT ADDRESS 2023-06-08 PH1 142.69 mg  Manufacturing Process Information  Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Term	Product-Env-Stew	vards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Authorized Representative* Tit				Title - Representative			Phone - Representative*			Email - Representative*				
MC74LVX259DG LOG CMOS 8-BIT ADDRESS 2023-06-08 PH1 142.69 mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycl Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Product-Env-Stewards Product Env			oduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
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vel 1 - maximum time at peak temperature during soldering is 10-30 seconds		time at neak temperatu	ına dunina sal	doring is 10	20 sacands										
vei 1 - maximum time at peak temperature during soldering is 10-30 seconds or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	led					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromir contains a RoHS restricted substance inexce encompass all such components. Supplier ce as of the date that Supplier completes this fo Company acknowledges that Supplier may l independently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated dipless of an applicable quantity limit, please intifies that it gathered the information it prome. Supplier acknowledges that Company have relied on information provided by other by others, Supplier agrees that, at a mining and the Supplier enter into a written agree esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substational substance below which, if any, RoHS exemption by desired in this form using appropriate method will rely on this certification in determining ters in completing this form, and that Supplies have provided certification between the will respect to the identified part, the Company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects the company is the company that the company tha	ws of the European Union member states) of the pnce") in excess of the applicable quantity limit ide in you believe may apply. If the part is an assembly is to ensure its accuracy and that such information the compliance of its products with European Union may not have independently verified such informs regarding their contributions to the part, and tho terms and conditions of that agreement, including the provides in this formation information the Supplier provides in this formation.	entified above. If a y with lower level is true and correct on member state la nation. However, in se certifications are any warranty rigl	n homogeneous material within the part components, the declaration shall t to the best of its knowledge and belief, aws that implement the RoHS Directive. In situations where Supplier has not e at least as comprehensive as the hts and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	cceptance *	Accepted					
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per	the definition above except for defined Ro	oHS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recruired by the					
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the					

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.73	mg	Supplier	Silicon (Si)	7440-21-3		2.73	mg
Die Attach	4.85	mg	Supplier	Silver (Ag)	7440-22-4		3.6375	mg
			Supplier	Epoxy resins	129915-35-1		1.2125	mg
Lead Frame	75.92	mg	Supplier	Silver (Ag)	7440-22-4		0.7592	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1518	mg
			Supplier	Iron (Fe)	7439-89-6		1.9739	mg
			Supplier	Copper (Cu)	7440-50-8		73.035	mg
Mold Compound-Black	55.11	mg		Epoxy Phenol Resin	proprietary data		5.7866	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		49.3234	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Au	0.35	mg	Supplier	Gold (Au)	7440-57-5		0.35	mg